

Application No.: 10/776,227Docket No.: 4459-139**AMENDMENTS TO THE SPECIFICATION:**

Please amend the paragraph on page 1, beginning at line 18 as follows:

As the need has arisen for lighter and more complex electronic devices, the semiconductor chip has to be manufactured for having more leads or contacts for inputting and outputting signals. For example, in a conventional plastic ball grid array (PBGA) package 10 shown in Fig. 1, a semiconductor chip 12 adheres to a substrate 14 by means of an adhesive layer 16. Bonding wires 18 are used to electrically connect the semiconductor chip 12 to the substrate 14 and an encapsulant 20 encapsulates the semiconductor chip 12 and the bonding wires 18. A plurality of solder balls 22 are disposed on the bottom surface of the substrate 14 for being attached to an external circuit board.

Please amend the paragraph on page 3, beginning at line 25 as follows:

Now referring to Fig. [[1]]2, it depicts a semiconductor package 100 according to an embodiment of the present invention. The semiconductor package 100 is a ball grid array package and has a carrier, such as a circuit board or substrate 114, and a chip 112. A plurality of spacers 116 are disposed on the substrate 114, and then the chip 112 is disposed on the spacers 116 and electrically connected to the substrate 114 by bonding wires 118. An encapsulant 120 encapsulates the chip 112, the spacers 116, and the bonding wires 118. A plurality of contacts, such as solder balls 122, are electrically connected to the bonding wires 118 and disposed on the bottom surface of the substrate 114 for being attached to an external circuit of an external circuit board.

Abstract:

Please replace the current Abstract with the following replacement/new Abstract